

# **Description**

The AON7422E-HXY uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =80 A

 $R_{DS(ON)} < 6 \text{ m}\Omega$  @  $V_{GS}=10V$ 

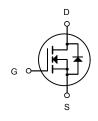
### **Application**

Battery protection

Load switch

Uninterruptible power supply

DFN3X3-8L



N-Channel MOSFET

# **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
AON7422E-HXY	DFN3X3-8L	80N03DF XXX YYYY	5000

## Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Symbol	Parameter Rating		Units	
VDS	Drain-Source Voltage	30	V	
VGS	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	80	А	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	50	А	
IDM	Pulsed Drain Current <sup>2</sup>	162	А	
EAS	Single Pulse Avalanche Energy³	144.7	mJ	
IAS	Avalanche Current	53.8	А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	62.5	W	
TSTG	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
ReJA	Thermal Resistance Junction-ambient <sup>1</sup>	62	°C/W	
R₀JC	Thermal Resistance Junction-Case <sup>1</sup>	2.4	°C/W	



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.0213		V/°C
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A		4.7	6	0
$R_{DS(ON)}$		V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		5.9	8	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V V I 050::A	1.0	1.5	2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.73		mV/°C
	Danier Courses I andrews Courses	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		26.5		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.4	2.8	Ω
Qg	Total Gate Charge (4.5V)			31.6		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		8.6		nC
$Q_{gd}$	Gate-Drain Charge			11.7		
T <sub>d(on)</sub>	Turn-On Delay Time			9		
T <sub>r</sub>	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		19		
T <sub>d(off)</sub>	Turn-Off Delay Time			58		ns
T <sub>f</sub>	Fall Time			15.2		
C <sub>iss</sub>	Input Capacitance			3075	4000	
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		400	530	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			315		

#### **Diode Characteristics**

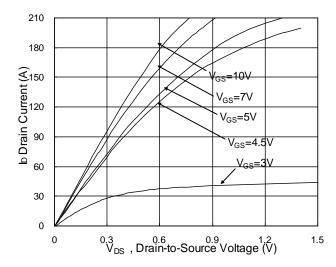
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,5</sup>	V V OV Force Current			80	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			162	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=30A , dI/dt=100A/μs ,		18		nS
$Q_{rr}$	Reverse Recovery Charge	T <sub>J</sub> =25°C		8		nC

## Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\,\leq\,300\text{us}$  , duty cycle  $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =53.8A
- 4.The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

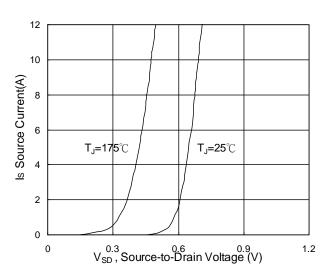


Fig.3 Forward Characteristics of Reverse

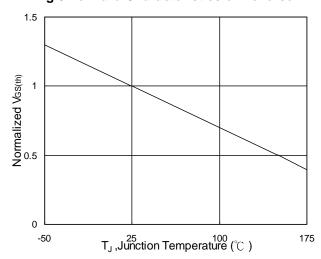


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

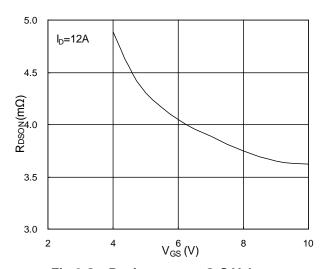


Fig.2 On-Resistance vs. G-S Voltage

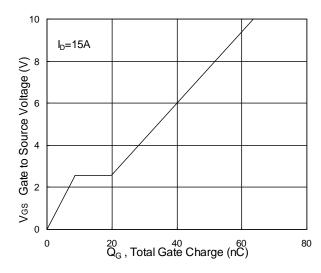


Fig.4 Gate-Charge Characteristics

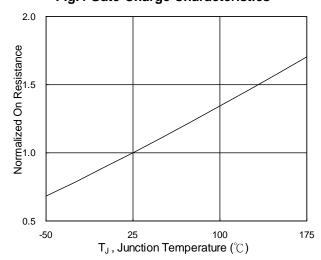
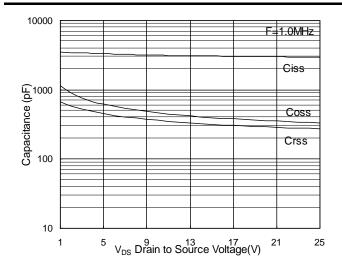


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



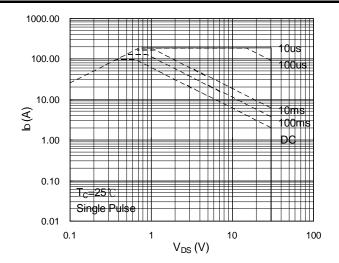


Fig.7 Capacitance

Fig.8 Safe Operating Area

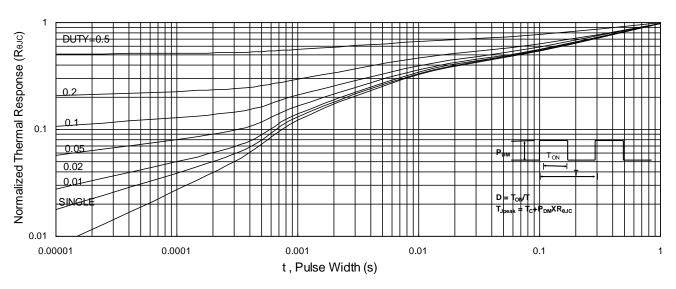


Fig.9 Normalized Maximum Transient Thermal Impedance

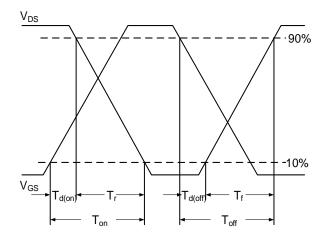


Fig.10 Switching Time Waveform

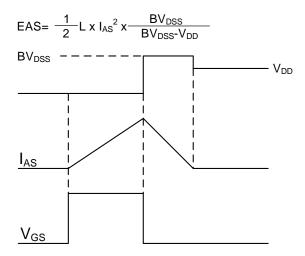
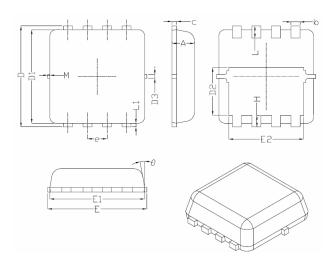


Fig.11 Unclamped Inductive Switching Waveform

# N-Channel Enhancement Mode MOSFET

# **DFN3X3-8L Package Information**



Sumb al	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10°	12 <sup>°</sup>	



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